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PATENT
Attorney Docket No. ASC-049C1
(120237/156689)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:	Fitzgerald		
SERIAL NO.:	10/774,890	GROUP NO.:	2818
FILING DATE:	February 9, 2004	EXAMINER:	Tran, Mai Huong C.
TITLE:	RELAXED SiGe PLATFORM FOR HIGH SPEED CMOS ELECTRONICS AND HIGH SPEED ANALOG CIRCUITS		

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicant hereby makes of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. In accordance with the U.S. Patent Office's partial waiver of the requirement under 37 C.F.R. 1.98(a)(2)(i), only copies of the non-patent publications are enclosed.

REMARKS

In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed (CHECK ONE):

☒ (1) within three (3) months of the **filing date** of a national application other than a continued prosecution application under 37 C.F.R. 1.53(d), or within three (3) months of the **date of entry of the national stage** as set forth in 37 C.F.R. 1.491 in an international application, or before the mailing of the **first Office action** on the merits, or before the mailing of a **first Office action** after the filing of a request for continued examination under 37 C.F.R. 1.114; or

☐ (2) after the period defined in (1) but before the mailing date of a **final action** or a **notice of allowance** under 37 C.F.R. 1.311, and

☐ the requisite Statement is below, **OR**

☐ the requisite fee under 37 C.F.R. 1.17(p), namely **$180.00**, is included herein, or

☐ (3) after the mailing date of a **final action** or **notice of allowance** but before the payment of the **issue fee, AND**

☐ the requisite Statement is below, **AND**

☐ the requisite petition fee under 37 C.F.R. 1.17(p), namely **$180.00** is included herein.

It is respectfully requested that each of the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application.

Respectfully submitted,

Date: Feb. 17, 2006

Reg. No. 44,381

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FORM PTO - 1449	ATTORNEY DOCKET NO.: ASC-049C1
INFORMATION DISCLOSURE STATEMENT	APPLICANT: Fitzgerald
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U.S. PATENT DOCUMENTS

EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A191	5,091,767	02/25/1992	Bean et al.			
	A192	5,571,373	11/05/1996	Krishna et al.			
	A193	5,633,202	05/27/1997	Brigham et al.			
	A194	5,710,450	01/20/1998	Chau et al.			
	A195	5,976,939	11/02/1999	Thompson et al.			
	A196	6,876,053	04/05/2005	Ma et al.			

OTHER ART, JOURNAL ARTICLES, ETC.

EXAM. INIT.	OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)	
	C135	Abstreiter et al., "Silicon/Germanium Strained Layer Superlattices," Journal of Crystal Growth, 95:431-438 (1989).
	C136	Auberton-Hervé et al., "SMART-CUT®: The Basic Fabrication Process for UNIBOND® SO1 Wafers," IEICE Transactions on Electronics, E80-C(3):358-363 (1997).
	C137	Cao et al., "0.18-μm Fully-Depleted Silicon-on -Insulator MOSFET's," IEEE Electron Device Letters, 18(6):251-253 (1997).
	C138	Chau et al., "Advanced CMOS Transistors in the Nanotechnology Era for High-Performance, Low-Power Logic Applications", pp. 26-30 (2004).
	C139	Eichinger et al., "Characterization of MBE Growth SiGe Superlattices with SIMS and RBS, Proceedings of the First International Symposium on Silicon Molecular Beam Epitaxy, 85(7):367-375 (1985).
	C140	Fair, "Concentration Profiles of Diffused Dopants in Silicon," Impurity Doping Processes in Silicon, Chapt. 7, pp. 318 -442 (1981).
	C141	Fair, "Quantified Conditions for Emitter-Misfit Dislocation Formation in Silicon," Journal of the Electrochemical Society, 125(6):923-926 (1978).
	C142	Fathy et al., "Formation of epitaxial layers of Ge on Si substrates by Ge implantation and oxidation"," Appl. Phys. Lett., 51(17):1337-1339 (1987).
	C143	Ghani et al., "Effect of oxygen on minority-carrier lifetime and recombination currents in $Si_{1-x}Ge_x$ heterostructure devices", Appl. Phys. Lett., 58(12):1317-1319 (1991).

EXAMINER	DATE CONSIDERED

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OTHER ART, JOURNAL ARTICLES, ETC.

EXAM. INIT.		OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)
	C144	Gibbons et al., "Limited reaction processing: Silicon epitaxy", Appl. Phys. Lett., 47(7):721-723 (1985).
	C145	Godbey et al., "A $Si_{0.7}Ge_{0.3}$ Strained Layer Etch Stop for the Generation of Bond and Etch Back SOI", IEEE SOS/SOI Tech. Conf. Proc., p. 143-144 (1989).
	C146	Gronet et al., "Growth of GeSi/Si strained-layer superlattices using limited reaction processing", J. Appl. Phys., 61(6):2407-2409 (1987).
	C147	Hobart et al., "Ultra-Cut: A Simple Technique for the Fabrication of SOI Substrates with Ultra-Thin (<5 nm) Silicon Films," Proceedings 1998 IEEE International SOI Conference, pp. 145-146 (1998).
	C148	Holländer et al., "Reduction of Dislocation Density of MBE-Grown $Si_{1-x}Ge_x$ Layers on (100) Si by Rapid Thermal Annealing", Thin Solid Films, 183:157-164 (1989).
	C149	Huang et al., "SiGe-on-insulator prepared by wafer bonding and layer transfer for high-performance field-effect transistors", Appl. Phys. Lett., 78(9):1267-1269 (2001).
	C150	Hull et al., "Structural Studies of GeSi/Si Heterostructures", Proceedings of the First International Symposium on Silicon Molecular Beam Epitaxy, 85(7): 376-384 (1985).
	C151	Ismail, et al., "Extremely high electron mobility in Si/SiGe modulation-doped heterostructures", Appl. Phys. Lett., 66(9):1077-1079 (1995).
	C152	Ismail, et al., "Gated Hall effect measurements in high-mobility *n*-type Si/SiGe modulation-doped heterostructures", Appl. Phys. Lett., 66(7):842-844 (1995)
	C153	Ismail, et al., "Identification of a Mobility-Limiting Scattering Mechanism in Modulation-Doped Si/SiGe Heterostructures", Physical Review Letters, 73(25):3447-3452 (1994).
	C154	Kasper, "Growth and Properties of Si/SiGe Superlattices", Surface Science, 174:630-639 (1986).
	C155	Maleville et al., "Physical Phenomena Involved in the Smart-Cut®Process", Electrochemical Society Proceedings, 96(3):34-46 (1996).
	C156	Mistry et al., "Delaying Forever: Uniaxial Strained Silicon Transistors in a 90nm CMOS Technology," Symposium on VLSI Technology Digest of Technical Papers, pp. 50-51 (2004).
	C157	Monroe et al., "Comparison of mobility-limiting mechanisms in high-mobility $Si_{1-x}Ge_x$ heterostructures", J. Vac. Sci. Technol. B, 11(4):1731-1737 (1993).
	C158	Noble et al., "Reduction in misfit dislocation density by the selective growth of $Si_{1-x}Ge_x$/Si in small areas", Appl. Phys. Lett., 56(1):51-53 (1990).

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OTHER ART, JOURNAL ARTICLES, ETC.

EXAM. INIT.		OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)
	C159	Schäffler et al., "Letter to the Editor, High-electron-mobility Si/SiGe heterostructures: influence of the relaxed SiGe buffer layer", Semicond. Sci. Technol., 7:260-266(1992).
	C160	Shifren et al., "Drive current enhancement in *p*-type metal-oxide-semiconductor field-effect transistors under shear uniaxial stress," Appl. Phys. Lett., 85(25):6188-6190 (2004).
	C161	Subbanna et al., "How SiGe Evolved into a Manufacturable Semiconductor Production Process", IEEE International Solid-State Circuits Conference, pp. 56, 67, 446 (1999).
	C162	Sugiyama et al., "Formation of strained-silicon layer on thin relaxed-SiGe/SiO_2/Si structure using SIMOX technology," Thin Solid Films, 369:199-202 (2000).
	C163	Taraschi et al, "Relaxed SiGe on Insulator Fabricated via Wafer Bonding and Layer Transfer: Etch-Back and Smart-Cut Alternatives," Electrochemical Society Proceedings, 2001(3):27-32 (2001).
	C164	Taraschi et al, "Relaxed SiGe-on-insulator fabricated via water bonding and etch back," J. Vac. Sci. Technol. B, 20(2):725-727 (2002).
	C165	Taraschi et al., "Strained-Si-on-Insulator (SSOI) and SiGe-on-Insulator (SGOI): Fabrication Obstacles and Solutions," Mat. Res. Soc. Symp. Proc., 745:105-110 (2003).

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